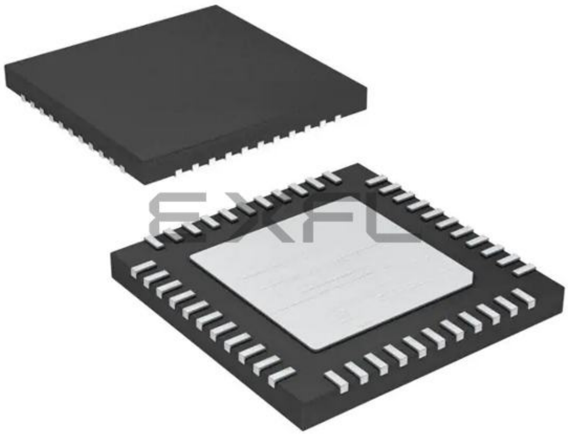

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 30x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf46k22-e-ml

TABLE 1-2: PIC18(L)F2XK22 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Number		Pin Name	Pin Type	Buffer Type	Description
PDIP, SOIC	QFN, UQFN				
20	17	VDD	P	—	Positive supply for logic and I/O pins.
8, 19	5, 16	VSS	P	—	Ground reference for logic and I/O pins.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power.

Note 1: Default pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are set.

2: Alternate pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are clear.

TABLE 1-3: PIC18(L)F4XK22 PINOUT I/O DESCRIPTIONS

Pin Number				Pin Name	Pin Type	Buffer Type	Description
PDIP	TQFP	QFN	UQFN				
2	19	19	17	RA0/C12IN0-/AN0			
				RA0	I/O	TTL	Digital I/O.
				C12IN0-	I	Analog	Comparators C1 and C2 inverting input.
				AN0	I	Analog	Analog input 0.
3	20	20	18	RA1/C12IN1-/AN1			
				RA1	I/O	TTL	Digital I/O.
				C12IN1-	I	Analog	Comparators C1 and C2 inverting input.
				AN1	I	Analog	Analog input 1.
4	21	21	19	RA2/C2IN+/AN2/DACOUT/VREF-			
				RA2	I/O	TTL	Digital I/O.
				C2IN+	I	Analog	Comparator C2 non-inverting input.
				AN2	I	Analog	Analog input 2.
				DACOUT	O	Analog	DAC Reference output.
				VREF-	I	Analog	A/D reference voltage (low) input.
5	22	22	20	RA3/C1IN+/AN3/VREF+			
				RA3	I/O	TTL	Digital I/O.
				C1IN+	I	Analog	Comparator C1 non-inverting input.
				AN3	I	Analog	Analog input 3.
				VREF+	I	Analog	A/D reference voltage (high) input.
6	23	23	21	RA4/C1OUT/SRQ/T0CKI			
				RA4	I/O	ST	Digital I/O.
				C1OUT	O	CMOS	Comparator C1 output.
				SRQ	O	TTL	SR latch Q output.
				T0CKI	I	ST	Timer0 external clock input.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power.

Note 1: Default pin assignment for P2B, T3CKI, CCP3/P3A and CCP2/P2A when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are set.

2: Alternate pin assignment for P2B, T3CKI, CCP3/P3A and CCP2/P2A when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are clear.

4.2 Register Definitions: Reset Control

REGISTER 4-1: RCON: RESET CONTROL REGISTER

R/W-0/0	R/W-q/u	U-0	R/W-1/q	R-1/q	R-1/q	R/W-q/u	R/W-0/q
IPEN	SBOREN(1)	—	$\overline{\text{RI}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	$\overline{\text{POR}}$(2)	$\overline{\text{BOR}}$
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
‘1’ = Bit is set	‘0’ = Bit is cleared	-n/n = Value at POR and BOR/Value at all other Resets
x = Bit is unknown	u = unchanged	q = depends on condition

bit 7 **IPEN:** Interrupt Priority Enable bit
1 = Enable priority levels on interrupts
0 = Disable priority levels on interrupts (PIC16CXXX Compatibility mode)

bit 6 **SBOREN:** BOR Software Enable bit(1)
If BOREN<1:0> = 01:
1 = BOR is enabled
0 = BOR is disabled
If BOREN<1:0> = 00, 10 or 11:
Bit is disabled and read as ‘0’.

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **$\overline{\text{RI}}$:** RESET Instruction Flag bit
1 = The RESET instruction was not executed (set by firmware or Power-on Reset)
0 = The RESET instruction was executed causing a device Reset (must be set in firmware after a code-executed Reset occurs)

bit 3 **$\overline{\text{TO}}$:** Watchdog Time-out Flag bit
1 = Set by power-up, CLRWDT instruction or SLEEP instruction
0 = A WDT time-out occurred

bit 2 **$\overline{\text{PD}}$:** Power-down Detection Flag bit
1 = Set by power-up or by the CLRWDT instruction
0 = Set by execution of the SLEEP instruction

bit 1 **$\overline{\text{POR}}$:** Power-on Reset Status bit(2)
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{\text{BOR}}$:** Brown-out Reset Status bit(3)
1 = A Brown-out Reset has not occurred (set by firmware only)
0 = A Brown-out Reset occurred (must be set by firmware after a POR or Brown-out Reset occurs)

Note 1: When CONFIG2L[2:1] = 01, then the SBOREN Reset state is ‘1’; otherwise, it is ‘0’.
2: The actual Reset value of $\overline{\text{POR}}$ is determined by the type of device Reset. See the notes following this register and **Section 4.7 “Reset State of Registers”** for additional information.
3: See Table 4-1.

Note 1: Brown-out Reset is indicated when $\overline{\text{BOR}}$ is ‘0’ and POR is ‘1’ (assuming that both $\overline{\text{POR}}$ and $\overline{\text{BOR}}$ were set to ‘1’ by firmware immediately after POR).
2: It is recommended that the $\overline{\text{POR}}$ bit be set after a Power-on Reset has been detected so that subsequent Power-on Resets may be detected.

4.5 Brown-out Reset (BOR)

PIC18(L)F2X/4XK22 devices implement a BOR circuit that provides the user with a number of configuration and power-saving options. The BOR is controlled by the BORV<1:0> and BOREN<1:0> bits of the CONFIG2L Configuration register. There are a total of four BOR configurations which are summarized in Table 4-1.

The BOR threshold is set by the BORV<1:0> bits. If BOR is enabled (any values of BOREN<1:0>, except '00'), any drop of V_{DD} below V_{BOR} for greater than T_{BOR} will reset the device. A Reset may or may not occur if V_{DD} falls below V_{BOR} for less than T_{BOR}. The chip will remain in Brown-out Reset until V_{DD} rises above V_{BOR}.

If the Power-up Timer is enabled, it will be invoked after V_{DD} rises above V_{BOR}; it then will keep the chip in Reset for an additional time delay, T_{PWRT}. If V_{DD} drops below V_{BOR} while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once V_{DD} rises above V_{BOR}, the Power-up Timer will execute the additional time delay.

BOR and the Power-on Timer (PWRT) are independently configured. Enabling BOR Reset does not automatically enable the PWRT.

The BOR circuit has an output that feeds into the POR circuit and rearms the POR within the operating range of the BOR. This early rearming of the POR ensures that the device will remain in Reset in the event that V_{DD} falls below the operating range of the BOR circuitry.

4.5.1 DETECTING BOR

When BOR is enabled, the $\overline{\text{BOR}}$ bit always resets to '0' on any BOR or POR event. This makes it difficult to determine if a BOR event has occurred just by reading the state of $\overline{\text{BOR}}$ alone. A more reliable method is to simultaneously check the state of both $\overline{\text{POR}}$ and $\overline{\text{BOR}}$. This assumes that the $\overline{\text{POR}}$ and $\overline{\text{BOR}}$ bits are reset to '1' by software immediately after any POR event. If $\overline{\text{BOR}}$ is '0' while $\overline{\text{POR}}$ is '1', it can be reliably assumed that a BOR event has occurred.

4.5.2 SOFTWARE ENABLED BOR

When BOREN<1:0> = 01, the BOR can be enabled or disabled by the user in software. This is done with the SBOREN control bit of the RCON register. Setting SBOREN enables the BOR to function as previously described. Clearing SBOREN disables the BOR entirely. The SBOREN bit operates only in this mode; otherwise it is read as '0'.

Placing the BOR under software control gives the user the additional flexibility of tailoring the application to the environment without having to reprogram the device to change BOR configuration. It also allows the user to tailor device power consumption in software by eliminating the incremental current that the BOR consumes. While the BOR current is typically very small, it may have some impact in low-power applications.

Note:	Even when BOR is under software control, the BOR Reset voltage level is still set by the BORV<1:0> Configuration bits. It cannot be changed by software.

4.5.3 DISABLING BOR IN SLEEP MODE

When BOREN<1:0> = 10, the BOR remains under hardware control and operates as previously described. Whenever the device enters Sleep mode, however, the BOR is automatically disabled. When the device returns to any other operating mode, BOR is automatically re-enabled.

This mode allows for applications to recover from brown-out situations, while actively executing code, when the device requires BOR protection the most. At the same time, it saves additional power in Sleep mode by eliminating the small incremental BOR current.

4.5.4 MINIMUM BOR ENABLE TIME

Enabling the BOR also enables the Fixed Voltage Reference (FVR) when no other peripheral requiring the FVR is active. The BOR becomes active only after the FVR stabilizes. Therefore, to ensure BOR protection, the FVR settling time must be considered when enabling the BOR in software or when the BOR is automatically enabled after waking from Sleep. If the BOR is disabled, in software or by reentering Sleep before the FVR stabilizes, the BOR circuit will not sense a BOR condition. The FVRST bit of the VREFCON0 register can be used to determine FVR stability.

REGISTER 10-4: ANSELB – PORTB ANALOG SELECT REGISTER

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **ANSB<5:0>:** RB<5:0> Analog Select bit
1 = Digital input buffer disabled
0 = Digital input buffer enabled

REGISTER 10-5: ANSELC – PORTC ANALOG SELECT REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	U-0	U-0
ANSC7	ANSC6	ANSC5	ANSC4	ANSC3	ANSC2	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-2 **ANSC<7:2>:** RC<7:2> Analog Select bit
1 = Digital input buffer disabled
0 = Digital input buffer enabled

bit 1-0 **Unimplemented:** Read as ‘0’

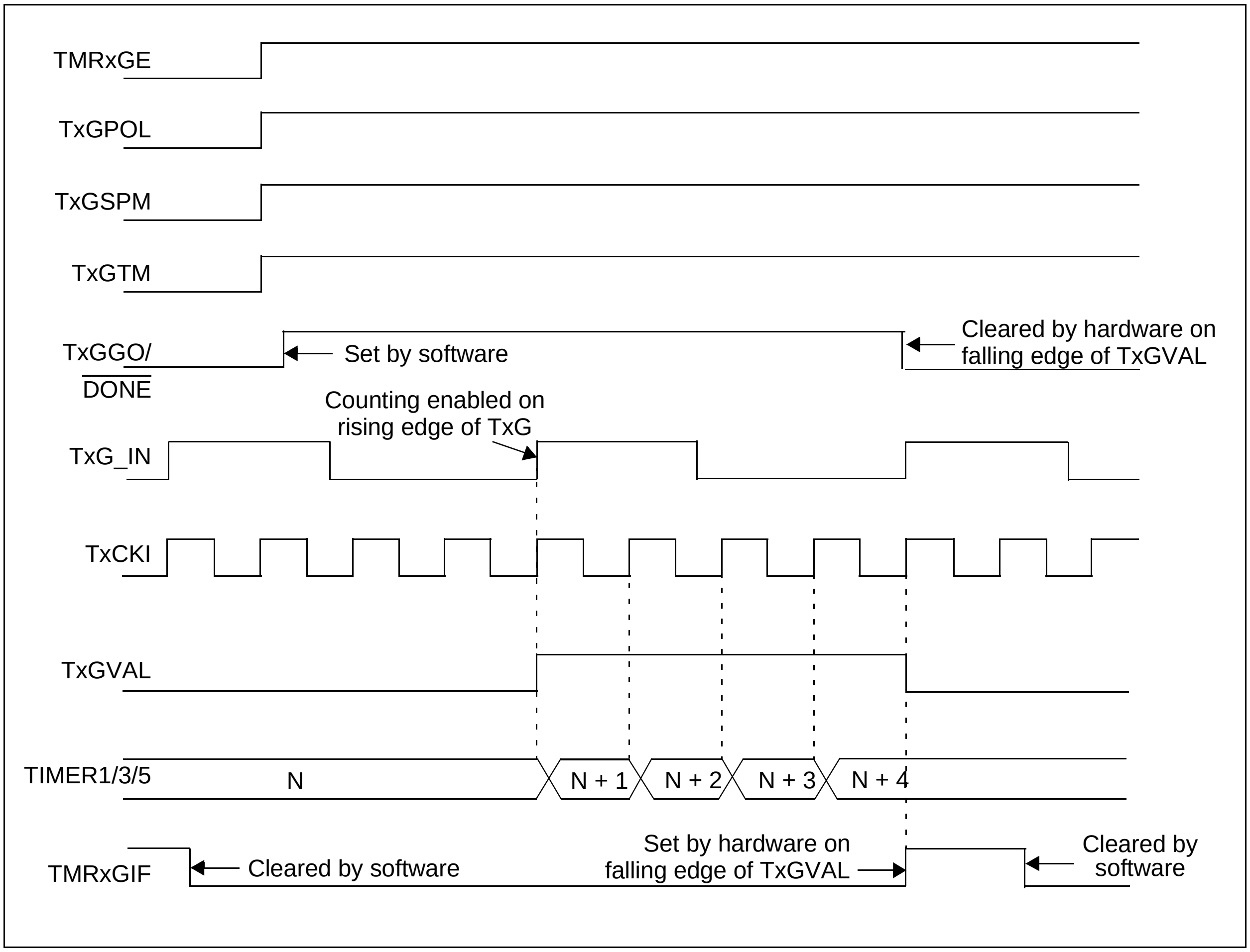
REGISTER 10-6: ANSELD – PORTD ANALOG SELECT REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
ANSD7	ANSD6	ANSD5	ANSD4	ANSD3	ANSD2	ANSD1	ANSD0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-0 **ANSD<7:0>:** RD<7:0> Analog Select bit
1 = Digital input buffer disabled
0 = Digital input buffer enabled

FIGURE 12-7: TIMER1/3/5 GATE SINGLE-PULSE AND TOGGLE COMBINED MODE



12.12 Peripheral Module Disable

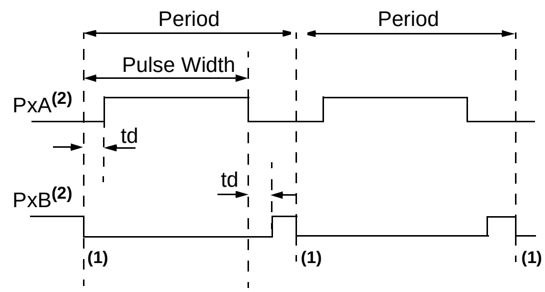
When a peripheral module is not used or inactive, the module can be disabled by setting the Module Disable bit in the PMD registers. This will reduce power consumption to an absolute minimum. Setting the PMD bits holds the module in Reset and disconnects the module's clock source. The Module Disable bits for Timer1 (TMR1MD), Timer3 (TMR3MD) and Timer5 (TMR5MD) are in the PMD0 Register. See **Section 3.0 "Power-Managed Modes"** for more information.

14.4.5 PROGRAMMABLE DEAD-BAND DELAY MODE

In half-bridge applications where all power switches are modulated at the PWM frequency, the power switches normally require more time to turn off than to turn on. If both the upper and lower power switches are switched at the same time (one turned on, and the other turned off), both switches may be on for a short period of time until one switch completely turns off. During this brief interval, a very high current (*shoot-through current*) will flow through both power switches, shorting the bridge supply. To avoid this potentially destructive shoot-through current from flowing during switching, turning on either of the power switches is normally delayed to allow the other switch to completely turn off.

In Half-Bridge mode, a digitally programmable dead-band delay is available to avoid shoot-through current from destroying the bridge power switches. The delay occurs at the signal transition from the non-active state to the active state. See Figure 14-16 for illustration. The lower seven bits of the associated PWMxCON register (Register 14-6) sets the delay period in terms of microcontroller instruction cycles (TCY or 4 TOSC).

FIGURE 14-16: EXAMPLE OF HALF-BRIDGE PWM OUTPUT



td = Dead-Band Delay

Note 1: At this time, the TMRx register is equal to the PRx register.

2: Output signals are shown as active-high.

FIGURE 14-17: EXAMPLE OF HALF-BRIDGE APPLICATIONS

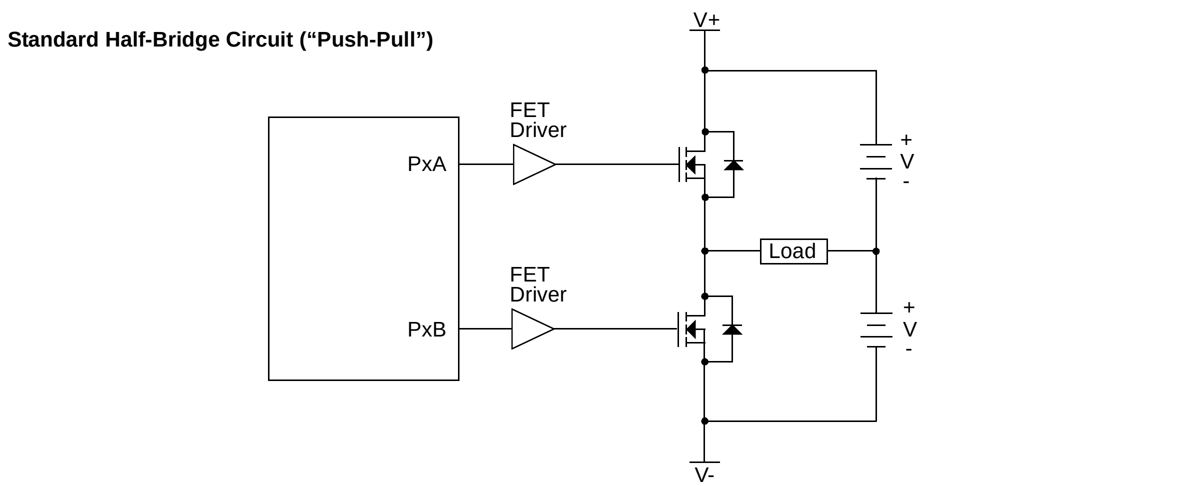
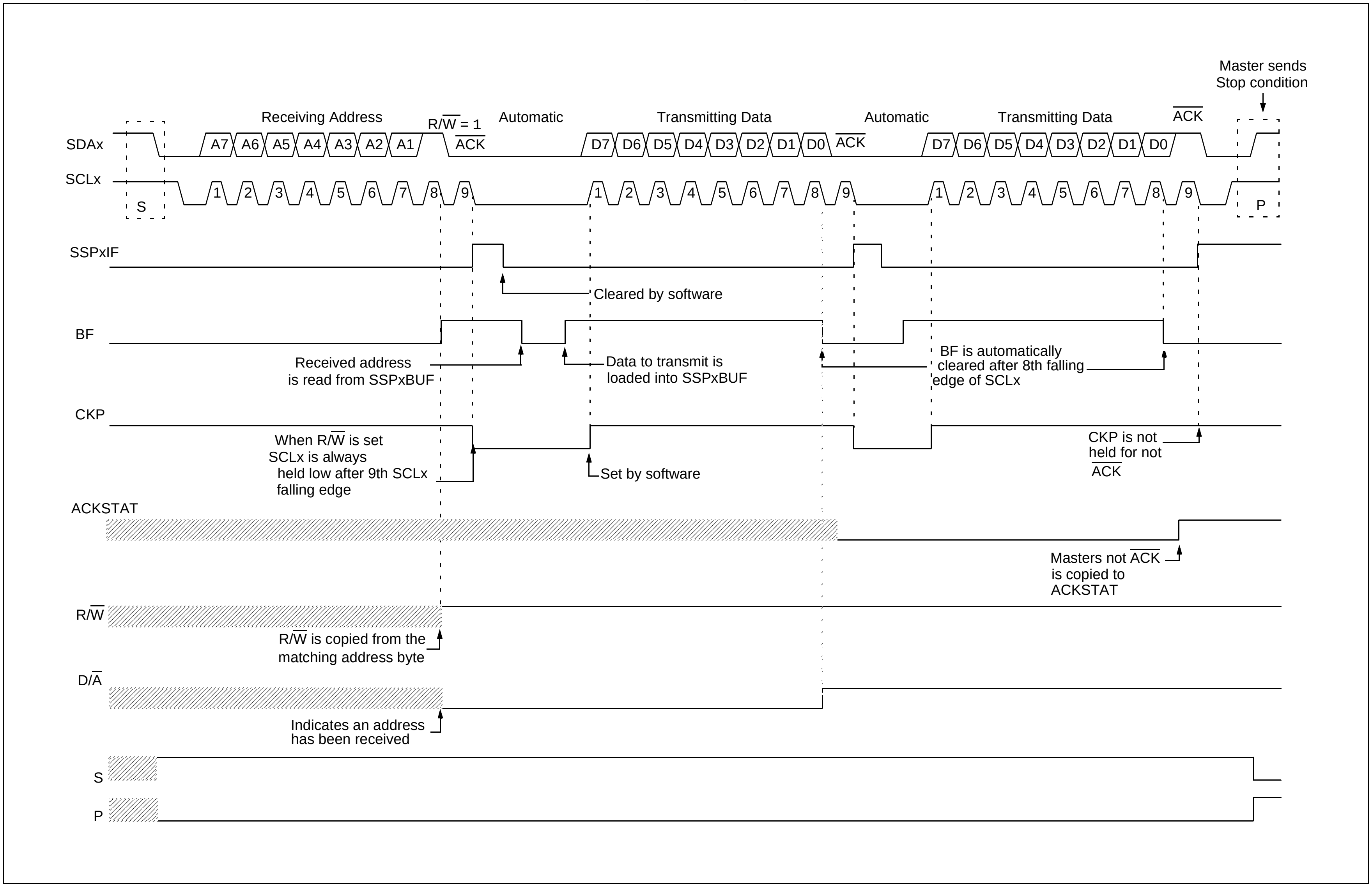


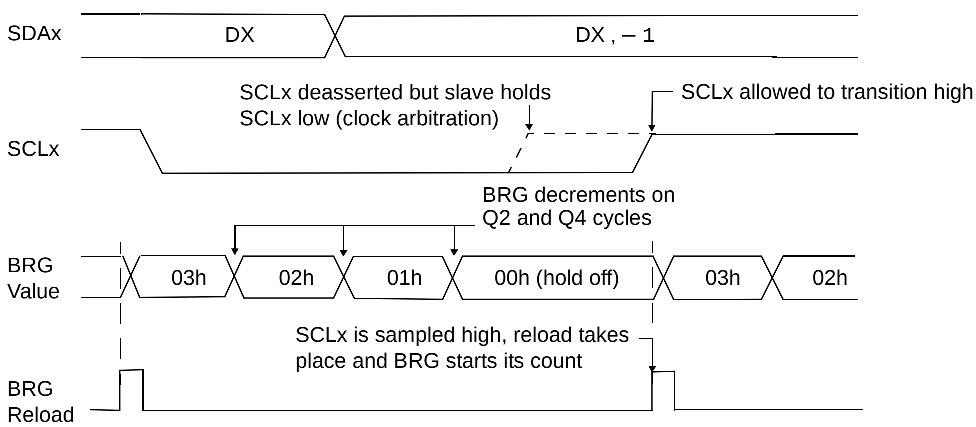
FIGURE 15-18: I²C SLAVE, 7-BIT ADDRESS, TRANSMISSION (AHEN = 0)



15.6.2 CLOCK ARBITRATION

Clock arbitration occurs when the master, during any receive, transmit or Repeated Start/Stop condition, releases the SCLx pin (SCLx allowed to float high). When the SCLx pin is allowed to float high, the Baud Rate Generator (BRG) is suspended from counting until the SCLx pin is actually sampled high. When the SCLx pin is sampled high, the Baud Rate Generator is reloaded with the contents of SSPxADD<7:0> and begins counting. This ensures that the SCLx high time will always be at least one BRG rollover count in the event that the clock is held low by an external device (Figure 15-25).

FIGURE 15-25: BAUD RATE GENERATOR TIMING WITH CLOCK ARBITRATION



15.6.3 WCOL STATUS FLAG

If the user writes the SSPxBUF when a Start, Restart, Stop, Receive or Transmit sequence is in progress, the WCOL is set and the contents of the buffer are unchanged (the write does not occur). Any time the WCOL bit is set it indicates that an action on SSPxBUF was attempted while the module was not Idle.

Note:	Because queueing of events is not allowed, writing to the lower 5 bits of SSPxCON2 is disabled until the Start condition is complete.

TABLE 16-9: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUDCON1	ABDOVF	RCIDL	DTRXP	CKTXP	BRG16	—	WUE	ABDEN	271
BAUDCON2	ABDOVF	RCIDL	DTRXP	CKTXP	BRG16	—	WUE	ABDEN	271
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	109
IPR1	—	ADIP	RC1IP	TX1IP	SSP1IP	CCP1IP	TMR2IP	TMR1IP	121
IPR3	SSP2IP	BCL2IP	RC2IP	TX2IP	CTMUIP	TMR5GIP	TMR3GIP	TMR1GIP	123
PIE1	—	ADIE	RC1IE	TX1IE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	117
PIE3	SSP2IE	BCL2IE	RC2IE	TX2IE	CTMUIE	TMR5GIE	TMR3GIE	TMR1GIE	119
PIR1	—	ADIF	RC1IF	TX1IF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	112
PIR3	SSP2IF	BCL2IF	RC2IF	TX2IF	CTMUIF	TMR5GIF	TMR3GIF	TMR1GIF	114
PMD0	UART2MD	UART1MD	TMR6MD	TMR5MD	TMR4MD	TMR3MD	TMR2MD	TMR1MD	52
RCSTA1	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	270
RCSTA2	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	270
SPBRG1	EUSART1 Baud Rate Generator, Low Byte								—
SPBRGH1	EUSART1 Baud Rate Generator, High Byte								—
SPBRG2	EUSART2 Baud Rate Generator, Low Byte								—
SPBRGH2	EUSART2 Baud Rate Generator, High Byte								—
ANSELC	ANSC7	ANSC6	ANSC5	ANSC4	ANSC3	ANSC2	—	—	150
ANSELD(1)	ANSD7	ANSD6	ANSD5	ANSD4	ANSD3	ANSD2	ANSD1	ANSD0	150
TRISB(2)	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	151
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	151
TRISD(1)	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	151
TXREG1	EUSART1 Transmit Register								—
TXSTA1	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	269
TXREG2	EUSART2 Transmit Register								—
TXSTA2	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	269

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for synchronous slave transmission.

Note 1: PIC18(L)F4XK22 devices.

2: PIC18(L)F2XK22 devices.

17.1.5 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON2 register. There are seven possible clock options:

- FOSC/2
- FOSC/4
- FOSC/8
- FOSC/16
- FOSC/32
- FOSC/64
- FRC (dedicated internal oscillator)

The time to complete one bit conversion is defined as TAD. One full 10-bit conversion requires 11 TAD periods as shown in Figure 17-3.

For correct conversion, the appropriate TAD specification must be met. See A/D conversion requirements in Table 27-22 for more information. Table 17-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

17.1.6 INTERRUPTS

The ADC module allows for the ability to generate an interrupt upon completion of an Analog-to-Digital Conversion. The ADC interrupt enable is the ADIE bit in the PIE1 register and the interrupt priority is the ADIP bit in the IPR1 register. The ADC interrupt flag is the ADIF bit in the PIR1 register. The ADIF bit must be cleared by software.

Note:	The ADIF bit is set at the completion of every conversion, regardless of whether or not the ADC interrupt is enabled.

This interrupt can be generated while the device is operating or while in Sleep. If the device is in Sleep, the interrupt will wake-up the device. Upon waking from Sleep, the next instruction following the `SLEEP` instruction is always executed. If the user is attempting to wake-up from Sleep and resume in-line code execution, the global interrupt must be disabled. If the global interrupt is enabled, execution will switch to the Interrupt Service Routine.

TABLE 17-1: ADC CLOCK PERIOD (TAD) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (TAD)		Device Frequency (FOSC)			
ADC Clock Source	**ADCS<2:0>**	**64 MHz**	**16 MHz**	**4 MHz**	**1 MHz**
FOSC/2	`000`	31.25 ns(2)	125 ns(2)	500 ns(2)	2.0 μs
FOSC/4	`100`	62.5 ns(2)	250 ns(2)	1.0 μs	4.0 μs(3)
FOSC/8	`001`	400 ns(2)	500 ns(2)	2.0 μs	8.0 μs(3)
FOSC/16	`101`	250 ns(2)	1.0 μs	4.0 μs(3)	16.0 μs(3)
FOSC/32	`010`	500 ns(2)	2.0 μs	8.0 μs(3)	32.0 μs(3)
FOSC/64	`110`	1.0 μs	4.0 μs(3)	16.0 μs(3)	64.0 μs(3)
FRC	`x11`	1-4 μs(1,4)	1-4 μs(1,4)	1-4 μs(1,4)	1-4 μs(1,4)

Legend: Shaded cells are outside of recommended range.

Note 1: The FRC source has a typical TAD time of 1.7 μs.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: The ADC clock period (TAD) and total ADC conversion time can be minimized when the ADC clock is derived from the system clock FOSC. However, the FRC oscillator source must be used when conversions are to be performed with the device in Sleep mode.

EXAMPLE 19-4: ROUTINE FOR CAPACITIVE TOUCH SWITCH

```
#include "p18cxxx.h"

#define COUNT 500                        //@ 8MHz = 125uS.
#define DELAY for(i=0;i<COUNT;i++)
#define OPENSW 1000                      //Un-pressed switch value
#define TRIP 300                         //Difference between pressed
                                         //and un-pressed switch
#define HYST 65                          //amount to change
                                         //from pressed to un-pressed
#define PRESSED 1
#define UNPRESSED 0

int main(void)
{
    unsigned int Vread;                  //storage for reading
    unsigned int switchState;
    int i;

    //assume CTMU and A/D have been set up correctly
    //see Example 25-1 for CTMU & A/D setup
    setup();

    CTMUCONHbits.CTMUEN = 1;             // Enable the CTMU
    CTMUCONLbits.EDG1STAT = 0;           // Set Edge status bits to zero
    CTMUCONLbits.EDG2STAT = 0;
    CTMUCONHbits.IDISSEN = 1;            //drain charge on the circuit
    DELAY;                               //wait 125us
    CTMUCONHbits.IDISSEN = 0;            //end drain of circuit

    CTMUCONLbits.EDG1STAT = 1;           //Begin charging the circuit
                                         //using CTMU current source
    DELAY;                               //wait for 125us
    CTMUCONLbits.EDG1STAT = 0;           //Stop charging circuit

    PIR1bits.ADIF = 0;                   //make sure A/D Int not set
    ADCON0bits.GO=1;                     //and begin A/D conv.
    while(!PIR1bits.ADIF);               //Wait for A/D convert complete

    Vread = ADRES;                       //Get the value from the A/D

    if(Vread < OPENSW - TRIP)
    {
        switchState = PRESSED;
    }
    else if(Vread > OPENSW - TRIP + HYST)
    {
        switchState = UNPRESSED;
    }
}
```

REGISTER 19-3: CTMUICON: CTMU CURRENT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ITRIM<5:0>						IRNG<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-2 **ITRIM<5:0>:** Current Source Trim bits

`011111` = Maximum positive change from nominal current
`011110`
.
.
.
`000001` = Minimum positive change from nominal current
`000000` = Nominal current output specified by IRNG<1:0>
`111111` = Minimum negative change from nominal current
.
.
.
`100010`
`100001` = Maximum negative change from nominal current

bit 1-0 **IRNG<1:0>:** Current Source Range Select bits (see Table 27-4)

`11` = 100 × Base current
`10` = 10 × Base current
`01` = Base current level
`00` = Current source disabled

TABLE 19-1: REGISTERS ASSOCIATED WITH CTMU MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page
CTMUCONH	CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG	323
CTMUCONL	EDG2POL	EDG2SEL<1:0>		EDG1POL	EDG1SEL<1:0>		EDG2STAT	EDG1STAT	324
CTMUICON	ITRIM<5:0>						IRNG<1:0>		325
IPR3	SSP2IP	BCL2IP	RC2IP	TX2IP	CTMUIP	TMR5GIP	TMR3GIP	TMR1GIP	123
PIE3	SSP2IE	BCL2IE	RC2IE	TX2IE	CTMUIE	TMR5GIE	TMR3GIE	TMR1GIE	119
PIR3	SSP2IF	BCL2IF	RC2IF	TX2IF	CTMUIF	TMR5GIF	TMR3GIF	TMR1GIF	114
PMD2	—	—	—	—	CTMUMD	CMP2MD	CMP1MD	ADCMD	54

Legend: — = unimplemented, read as ‘0’. Shaded bits are not used during CTMU operation.

21.0 FIXED VOLTAGE REFERENCE (FVR)

The Fixed Voltage Reference, or FVR, is a stable voltage reference, independent of VDD, with 1.024V, 2.048V or 4.096V selectable output levels. The output of the FVR can be configured to supply a reference voltage to the following:

- ADC input channel
- ADC positive reference
- Comparator positive input
- Digital-to-Analog Converter (DAC)

The FVR can be enabled by setting the FVREN bit of the VREFCON0 register.

21.1 Independent Gain Amplifiers

The output of the FVR supplied to the ADC, Comparators and DAC is routed through an independent programmable gain amplifier. The amplifier can be configured to amplify the 1.024V reference voltage by 1x, 2x or 4x, to produce the three possible voltage levels.

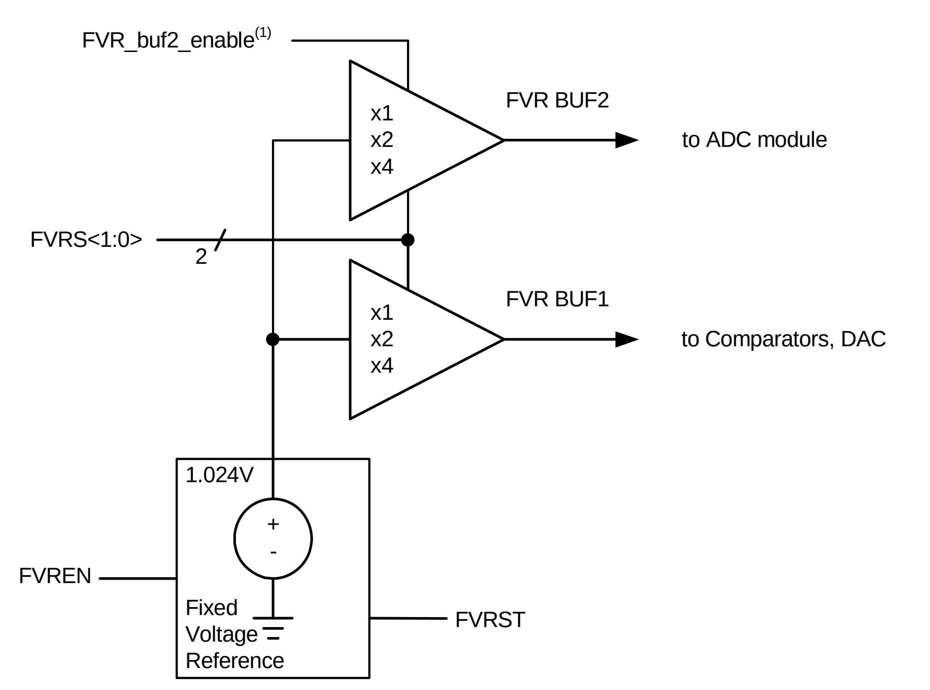
The FVRS<1:0> bits of the VREFCON0 register are used to enable and configure the gain amplifier settings for the reference supplied to the DAC and Comparator modules. When the ADC module is configured to use the FVR output, (FVR BUF2) the reference is buffered through an additional unity gain amplifier. This buffer is disabled if the ADC is not configured to use the FVR.

For specific use of the FVR, refer to the specific module sections: **Section 17.0 “Analog-to-Digital Converter (ADC) Module”**, **Section 22.0 “Digital-to-Analog Converter (DAC) Module”** and **Section 18.0 “Comparator Module”**.

21.2 FVR Stabilization Period

When the Fixed Voltage Reference module is enabled, it requires time for the reference and amplifier circuits to stabilize. Once the circuits stabilize and are ready for use, the FVRST bit of the VREFCON0 register will be set. See Table 27-3 for the minimum delay requirement.

FIGURE 21-1: VOLTAGE REFERENCE BLOCK DIAGRAM



Note 1: FVR_buf2_enable = ‘1’ when (ADON = ‘1’) AND [(PVCFG<1:0> = ‘10’) OR (CHS<4:0> = ‘11111’)]

REGISTER 24-11: CONFIG7H: CONFIGURATION REGISTER 7 HIGH

U-0	R/C-1	U-0	U-0	U-0	U-0	U-0	U-0
—	EBTRB	—	—	—	—	—	—
bit 7							bit 0

Legend:	
R = Readable bit	U = Unimplemented bit, read as ‘0’
-n = Value when device is unprogrammed	C = Clearable only bit

bit 7 **Unimplemented:** Read as ‘0’

bit 6 **EBTRB:** Boot Block Table Read Protection bit
1 = Boot Block not protected from table reads executed in other blocks
0 = Boot Block protected from table reads executed in other blocks

bit 5-0 **Unimplemented:** Read as ‘0’

REGISTER 24-12: DEVID1: DEVICE ID REGISTER 1

R	R	R	R	R	R	R	R
DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0
bit 7							bit 0

Legend:	
R = Readable bit	U = Unimplemented bit, read as ‘0’
-n = Value when device is unprogrammed	C = Clearable only bit

bit 7-5 **DEV<2:0>:** Device ID bits
These bits, together with DEV<10:3> in DEVID2, determine the device ID.
See Table 24-2 for complete Device ID list.

bit 4-0 **REV<4:0>:** Revision ID bits
These bits indicate the device revision.

REGISTER 24-13: DEVID2: DEVICE ID REGISTER 2

R	R	R	R	R	R	R	R
DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3
bit 7							bit 0

Legend:	
R = Readable bit	U = Unimplemented bit, read as ‘0’
-n = Value when device is unprogrammed	C = Clearable only bit

bit 7-0 **DEV<10:3>:** Device ID bits
These bits, together with DEV<2:0> in DEVID1, determine the device ID.
See Table 24-2 for complete Device ID list.

GOTO — Unconditional Branch

Syntax:	GOTO k
Operands:	$0 \le k \le 1048575$
Operation:	$k \rightarrow$ PC<20:1>
Status Affected:	None

Encoding:

1st word (k<7:0>)	1110	1111	$k_7$kkk	kkkk$_0$
2nd word(k<19:8>)	1111	k_{19}kkk	kkkk	kkkk$_8$

Description: GOTO allows an unconditional branch anywhere within entire 2-Mbyte memory range. The 20-bit value 'k' is loaded into PC<20:1>. GOTO is always a 2-cycle instruction.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>,	No operation	Read literal 'k'<19:8>, Write to PC
No operation	No operation	No operation	No operation

Example: `GOTO THERE`

After Instruction
PC = Address (THERE)

INCF — Increment f

Syntax:	INCF f {,d {,a}}
Operands:	$0 \le f \le 255$ $d \in [0,1]$ $a \in [0,1]$
Operation:	(f) + 1 $\rightarrow$ dest
Status Affected:	C, DC, N, OV, Z

Encoding:

0010	10da	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default).
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `INCF CNT, 1, 0`

Before Instruction
CNT = FFh
Z = 0
C = ?
DC = ?

After Instruction
CNT = 00h
Z = 1
C = 1
DC = 1

SUBFSR — Subtract Literal from FSR

Syntax:	SUBFSR f, k
Operands:	$0 \le k \le 63$ $f \in [\,0, 1, 2\,]$
Operation:	FSR(f) – k → FSRf
Status Affected:	None
Encoding:	`1110` `1001` `ffkk` `kkkk`
Description:	The 6-bit literal ‘k’ is subtracted from the contents of the FSR specified by ‘f’.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination

Example: `SUBFSR 2, 23h`

Before Instruction
FSR2 = 03FFh
After Instruction
FSR2 = 03DCh

SUBULNK — Subtract Literal from FSR2 and Return

Syntax:	SUBULNK k
Operands:	$0 \le k \le 63$
Operation:	FSR2 – k → FSR2 (TOS) → PC
Status Affected:	None
Encoding:	`1110` `1001` `11kk` `kkkk`
Description:	The 6-bit literal ‘k’ is subtracted from the contents of the FSR2. A `RETURN` is then executed by loading the PC with the TOS. The instruction takes two cycles to execute; a `NOP` is performed during the second cycle. This may be thought of as a special case of the `SUBFSR` instruction, where f = 3 (binary ‘`11`’); it operates only on FSR2.
Words:	1
Cycles:	2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination
No Operation	No Operation	No Operation	No Operation

Example: `SUBULNK 23h`

Before Instruction
FSR2 = 03FFh
PC = 0100h
After Instruction
FSR2 = 03DCh
PC = (TOS)

FIGURE 28-50: PIC18F2X/4XK22 TYPICAL IDD: PRI_RUN EC MEDIUM POWER

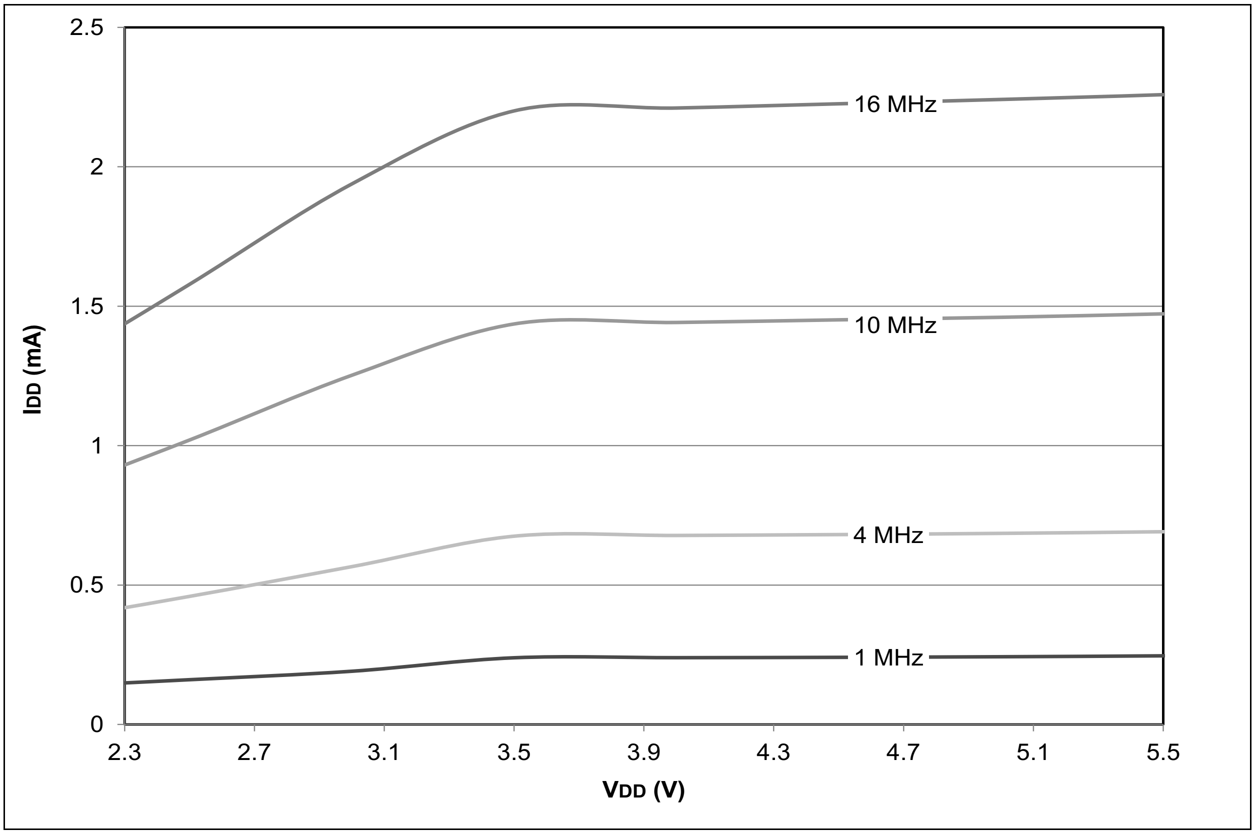


FIGURE 28-51: PIC18F2X/4XK22 MAXIMUM IDD: PRI_RUN EC MEDIUM POWER

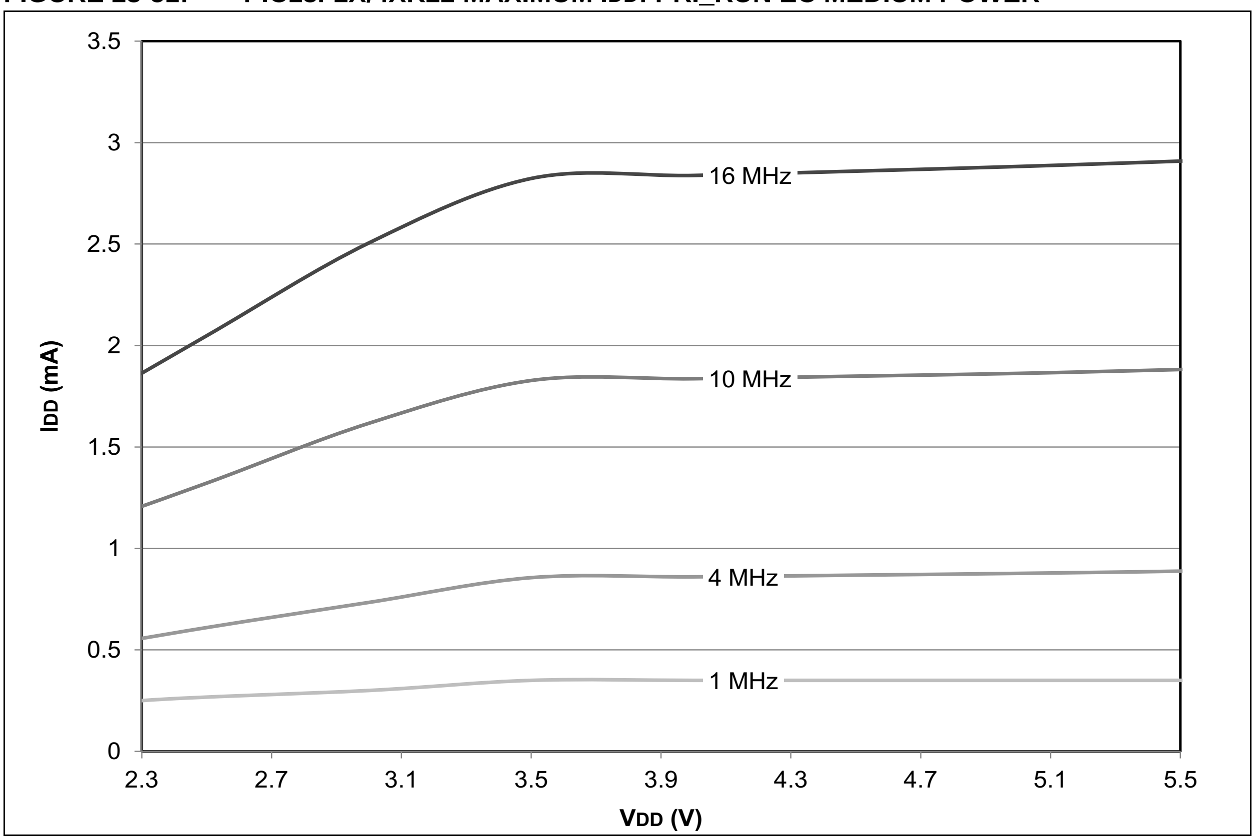


FIGURE 28-94: PIC18(L)F2X/4XK22 TYPICAL FIXED VOLTAGE REFERENCE 1x OUTPUT

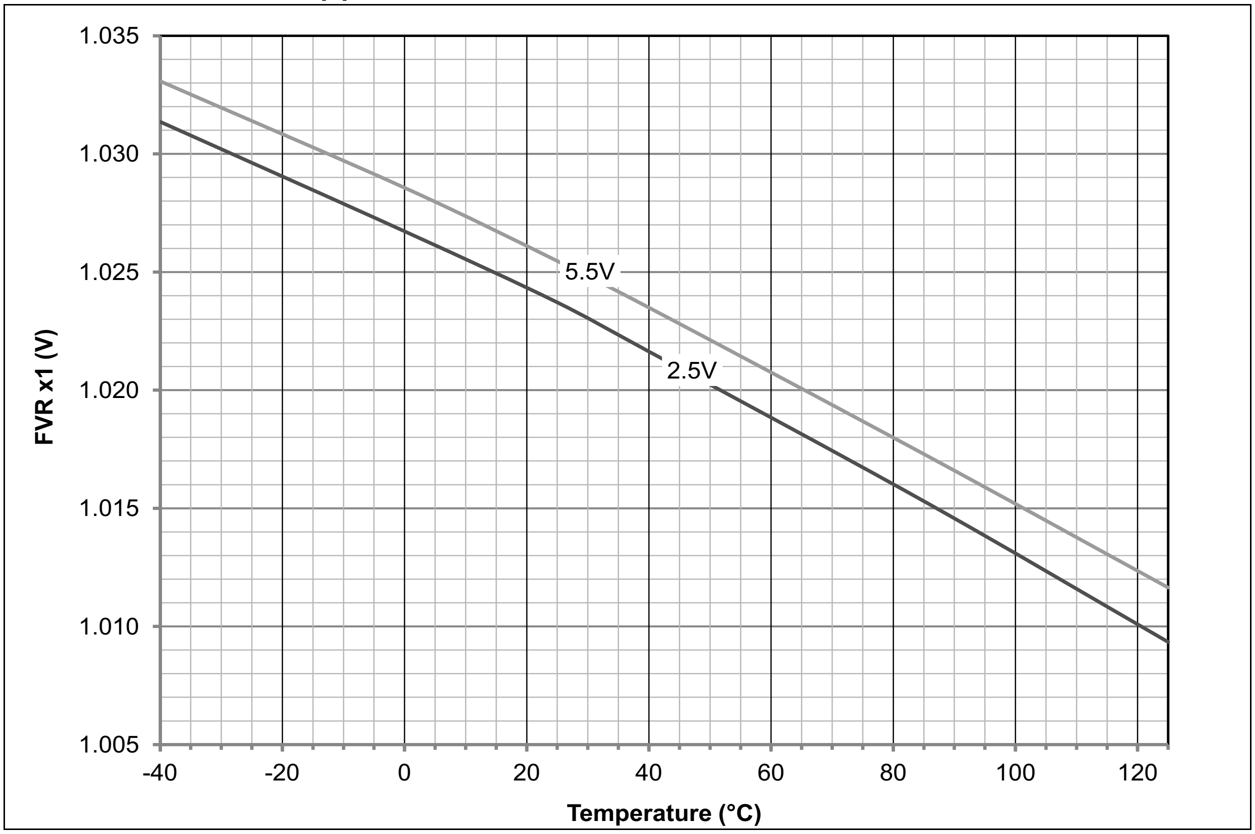
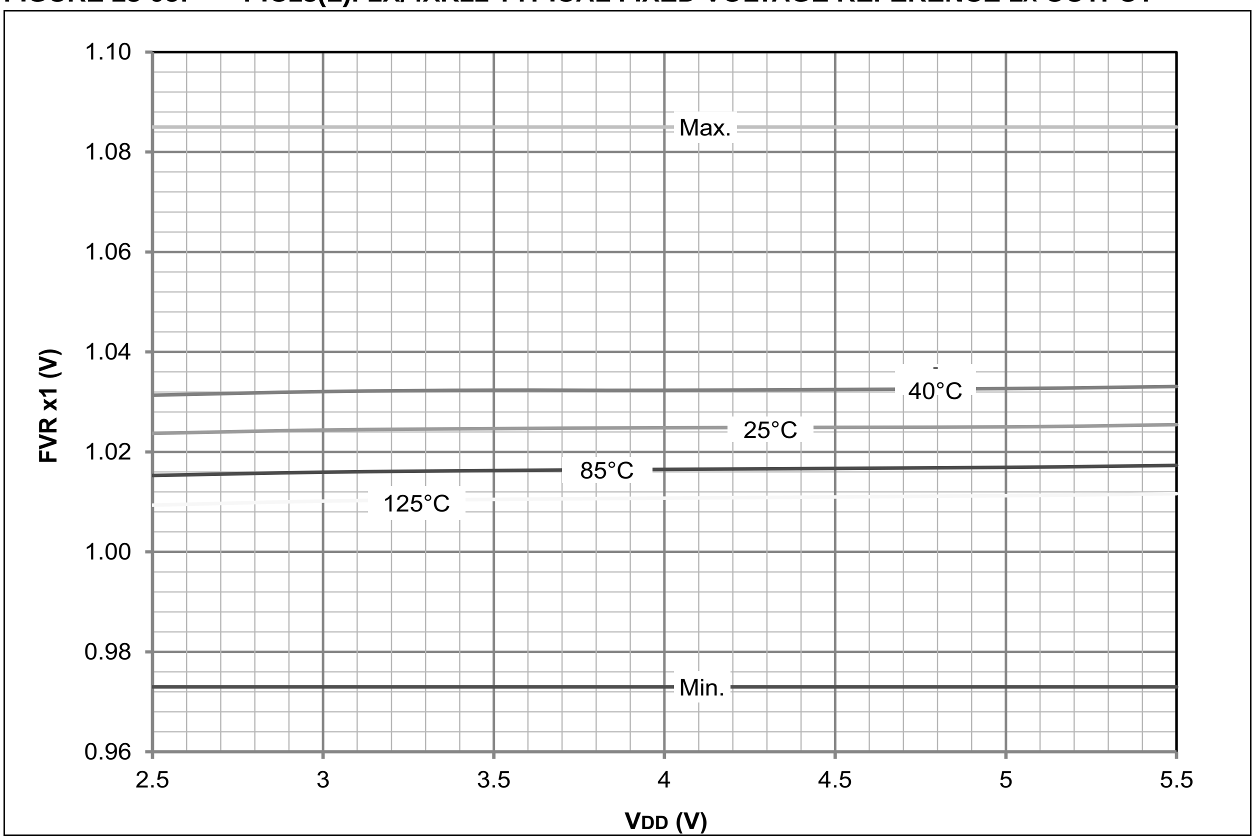
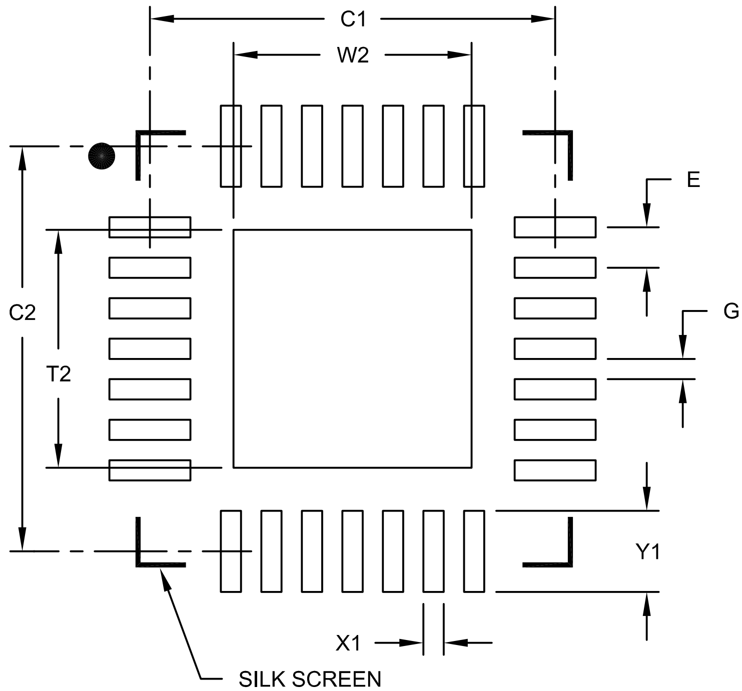


FIGURE 28-95: PIC18(L)F2X/4XK22 TYPICAL FIXED VOLTAGE REFERENCE 1x OUTPUT



28-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 4x4 mm Body [UQFN]
With 0.40 mm Contact Length

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Optional Center Pad Width	W2			2.35
Optional Center Pad Length	T2			2.35
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

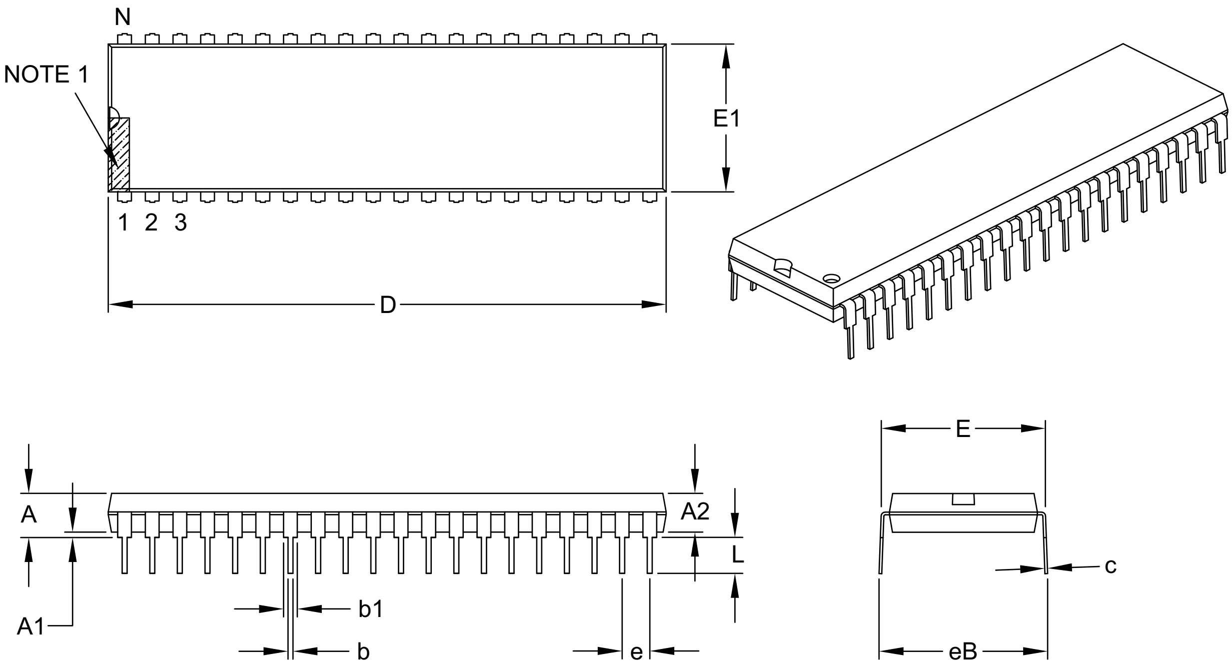
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2152A

40-Lead Plastic Dual In-Line (P) – 600 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	40		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.250
Molded Package Thickness	A2	.125	–	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.590	–	.625
Molded Package Width	E1	.485	–	.580
Overall Length	D	1.980	–	2.095
Tip to Seating Plane	L	.115	–	.200
Lead Thickness	c	.008	–	.015
Upper Lead Width	b1	.030	–	.070
Lower Lead Width	b	.014	–	.023
Overall Row Spacing §	eB	–	–	.700

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-016B